

# NPN SILICON GERMANIUM RF TRANSISTOR

# NESG3032M14

### NPN SiGe RF TRANSISTOR FOR LOW NOISE, HIGH-GAIN AMPLIFICATION 4-PIN LEAD-LESS MINIMOLD (M14, 1208 PACKAGE)

#### FEATURES

- The device is an ideal choice for low noise, high-gain amplification  
NF = 0.6 dB TYP. @  $V_{CE} = 2\text{ V}$ ,  $I_C = 6\text{ mA}$ ,  $f = 2.0\text{ GHz}$
- Maximum stable power gain: MSG = 20.5 dB TYP. @  $V_{CE} = 2\text{ V}$ ,  $I_C = 15\text{ mA}$ ,  $f = 2.0\text{ GHz}$
- SiGe HBT technology (UHS3) adopted:  $f_{max} = 110\text{ GHz}$
- 4-pin lead-less minimold (M14, 1208 package)

#### <R> ORDERING INFORMATION

Part Number	Order Number	Package	Quantity	Supplying Form
NESG3032M14	NESG3032M14-A	4-pin lead-less minimold (M14, 1208 package) (Pb-Free)	50 pcs (Non reel)	<ul style="list-style-type: none"> <li>• 8 mm wide embossed taping</li> <li>• Pin 1 (Collector), Pin 4 (NC) face the perforation side of the tape</li> </ul>
NESG3032M14-T3	NESG3032M14-T3-A		10 kpcs/reel	

**Remark** To order evaluation samples, contact your nearby sales office.  
Unit sample quantity is 50 pcs.

#### ABSOLUTE MAXIMUM RATINGS ( $T_A = +25^\circ\text{C}$ )

Parameter	Symbol	Ratings	Unit
Collector to Base Voltage	$V_{CBO}$	12.0	V
Collector to Emitter Voltage	$V_{CEO}$	4.3	V
Emitter to Base Voltage	$V_{EBO}$	1.5	V
Collector Current	$I_C$	35	mA
Total Power Dissipation	$P_{tot}^{Note}$	150	mW
Junction Temperature	$T_j$	150	$^\circ\text{C}$
Storage Temperature	$T_{stg}$	-65 to +150	$^\circ\text{C}$

**Note** Mounted on  $1.08\text{ cm}^2 \times 1.0\text{ mm}$  (t) glass epoxy PWB

**Caution** Observe precautions when handling because these devices are sensitive to electrostatic discharge.

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Not all products and/or types are available in every country. Please check with an NEC Electronics sales representative for availability and additional information.

**ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = +25°C)**

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
DC Characteristics						
Collector Cut-off Current	I <sub>CBO</sub>	V <sub>CB</sub> = 5 V, I <sub>E</sub> = 0 mA	–	–	100	nA
Emitter Cut-off Current	I <sub>EBO</sub>	V <sub>EB</sub> = 1 V, I <sub>C</sub> = 0 mA	–	–	100	nA
DC Current Gain	h <sub>FE</sub> <sup>Note 1</sup>	V <sub>CE</sub> = 2 V, I <sub>C</sub> = 6 mA	220	300	380	–
RF Characteristics						
Insertion Power Gain	S <sub>21e</sub>   <sup>2</sup>	V <sub>CE</sub> = 2 V, I <sub>C</sub> = 15 mA, f = 2.0 GHz	15.0	17.5	–	dB
Noise Figure	NF	V <sub>CE</sub> = 2 V, I <sub>C</sub> = 6 mA, f = 2.0 GHz, Z <sub>S</sub> = Z <sub>Sopt</sub> , Z <sub>L</sub> = Z <sub>Lopt</sub>	–	0.60	0.85	dB
Associated Gain	G <sub>a</sub>	V <sub>CE</sub> = 2 V, I <sub>C</sub> = 6 mA, f = 2.0 GHz, Z <sub>S</sub> = Z <sub>Sopt</sub> , Z <sub>L</sub> = Z <sub>Lopt</sub>	–	17.5	–	dB
Reverse Transfer Capacitance	C <sub>re</sub> <sup>Note 2</sup>	V <sub>CB</sub> = 2 V, I <sub>E</sub> = 0 mA, f = 1 MHz	–	0.15	0.25	pF
Maximum Stable Power Gain	MSG <sup>Note 3</sup>	V <sub>CE</sub> = 2 V, I <sub>C</sub> = 15 mA, f = 2.0 GHz	17.5	20.5	–	dB
Gain 1 dB Compression Output Power	P <sub>O(1 dB)</sub>	V <sub>CE</sub> = 3 V, I <sub>C(set)</sub> = 20 mA, f = 2.0 GHz, Z <sub>S</sub> = Z <sub>Sopt</sub> , Z <sub>L</sub> = Z <sub>Lopt</sub>	–	12.5	–	dBm
3rd Order Intermodulation Distortion Output Intercept Point	OIP <sub>3</sub>	V <sub>CE</sub> = 3 V, I <sub>C(set)</sub> = 20 mA, f = 2.0 GHz, Z <sub>S</sub> = Z <sub>Sopt</sub> , Z <sub>L</sub> = Z <sub>Lopt</sub>	–	24.0	–	dBm

- Notes 1.** Pulse measurement: PW ≤ 350 μs, Duty Cycle ≤ 2%  
**2.** Collector to base capacitance when the emitter grounded

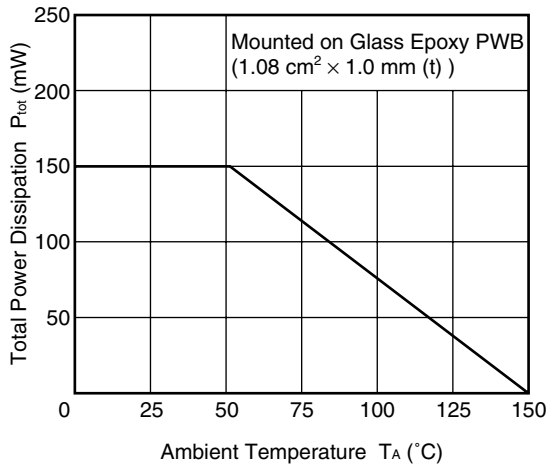
**3.**  $MSG = \left| \frac{S_{21}}{S_{12}} \right|$

**h<sub>FE</sub> CLASSIFICATION**

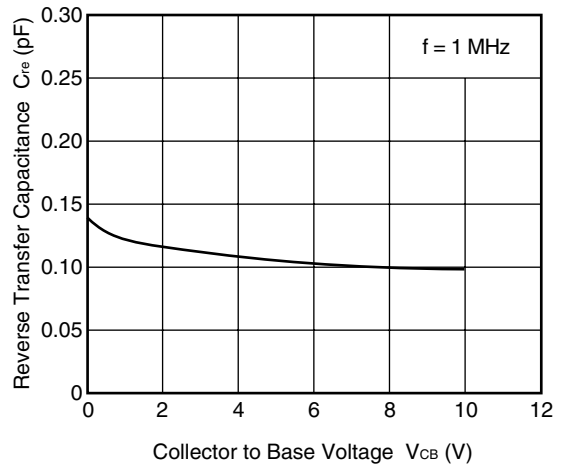
Rank	FB
Marking	zN
h <sub>FE</sub> Value	220 to 380

<R> TYPICAL CHARACTERISTICS (T<sub>A</sub> = +25°C, unless otherwise specified)

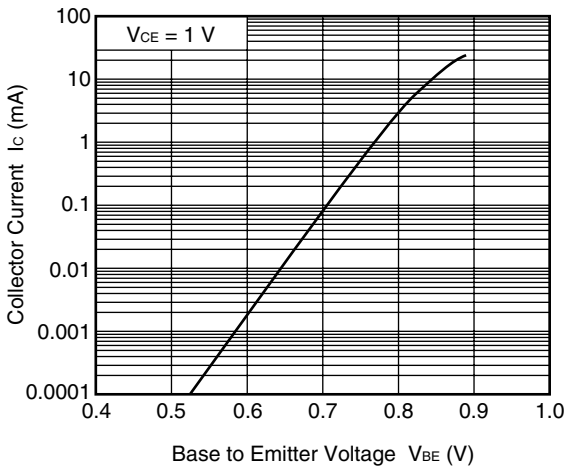
TOTAL POWER DISSIPATION vs. AMBIENT TEMPERATURE



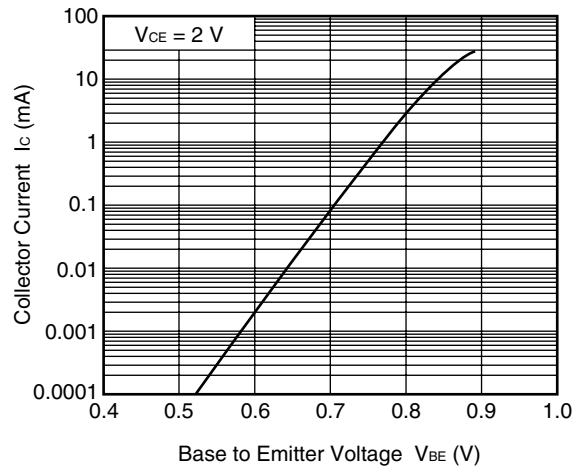
REVERSE TRANSFER CAPACITANCE vs. COLLECTOR TO BASE VOLTAGE



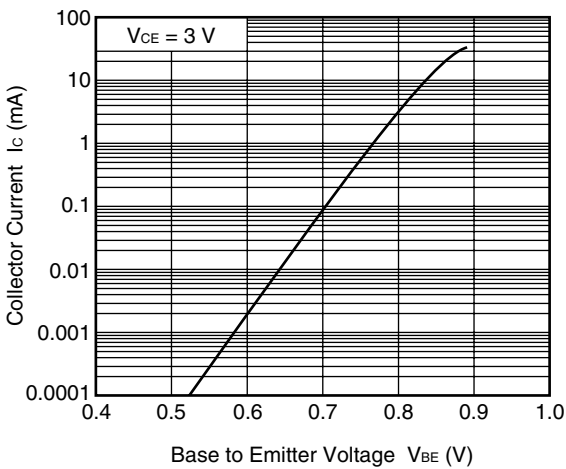
COLLECTOR CURRENT vs. BASE TO EMITTER VOLTAGE



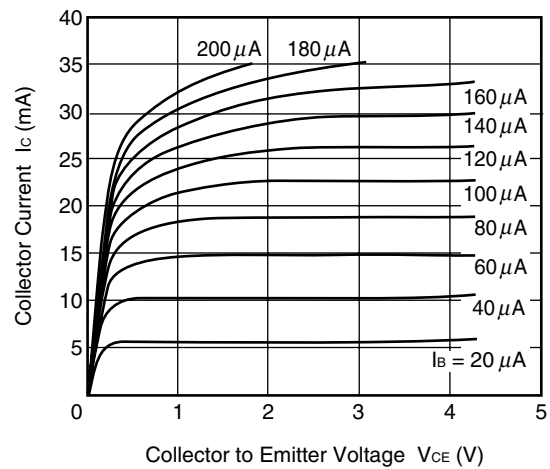
COLLECTOR CURRENT vs. BASE TO EMITTER VOLTAGE



COLLECTOR CURRENT vs. BASE TO EMITTER VOLTAGE

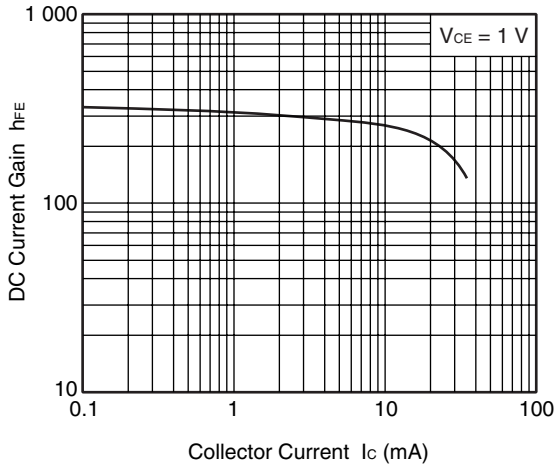


COLLECTOR CURRENT vs. COLLECTOR TO EMITTER VOLTAGE

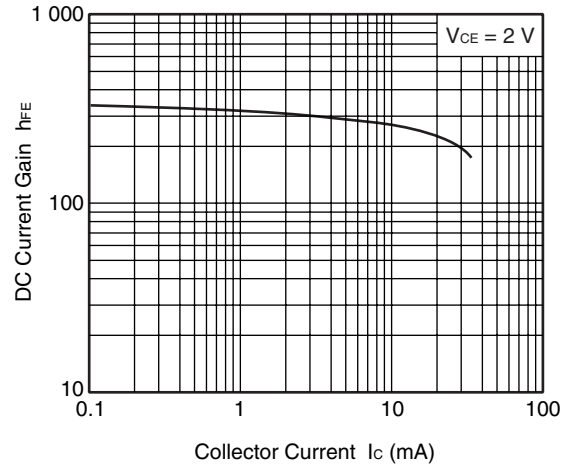


**Remark** The graphs indicate nominal characteristics.

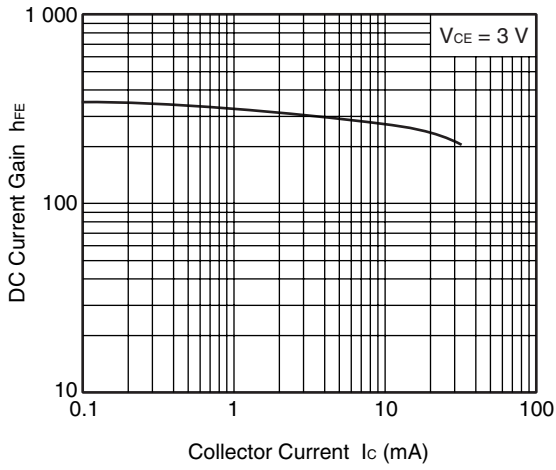
DC CURRENT GAIN vs.  
COLLECTOR CURRENT



DC CURRENT GAIN vs.  
COLLECTOR CURRENT

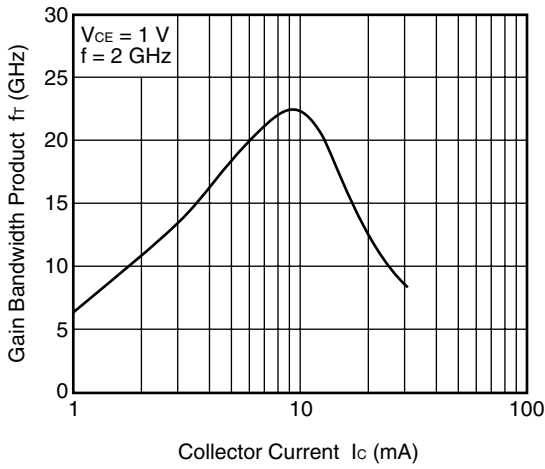


DC CURRENT GAIN vs.  
COLLECTOR CURRENT

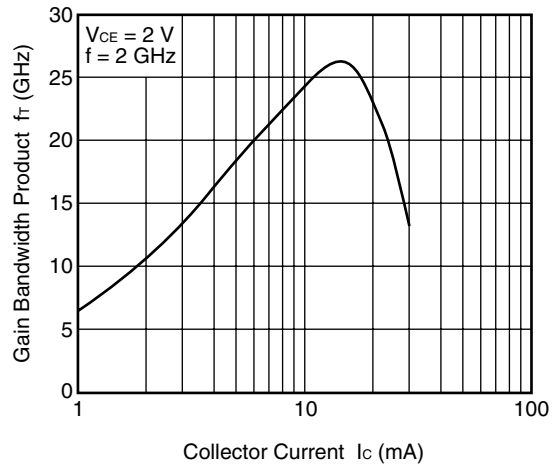


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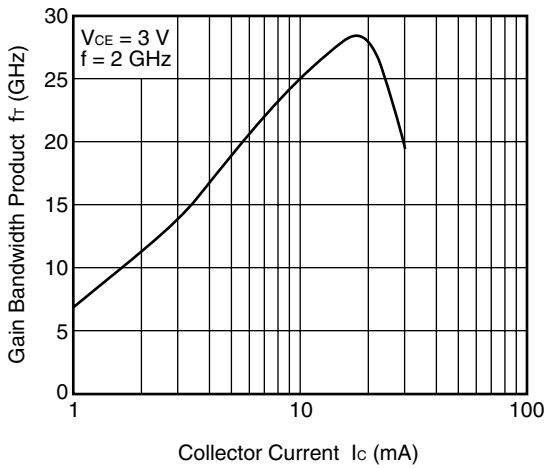
GAIN BANDWIDTH PRODUCT vs. COLLECTOR CURRENT



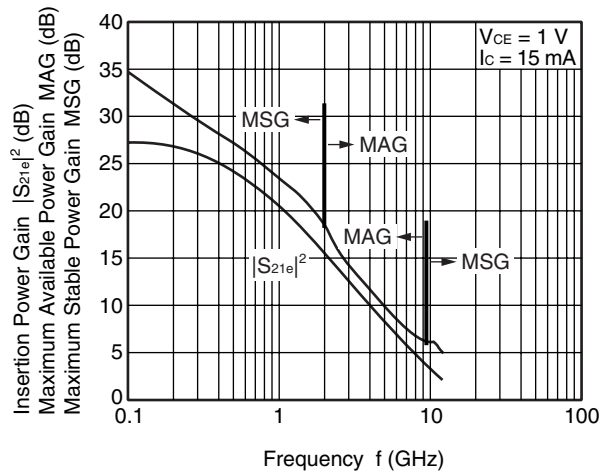
GAIN BANDWIDTH PRODUCT vs. COLLECTOR CURRENT



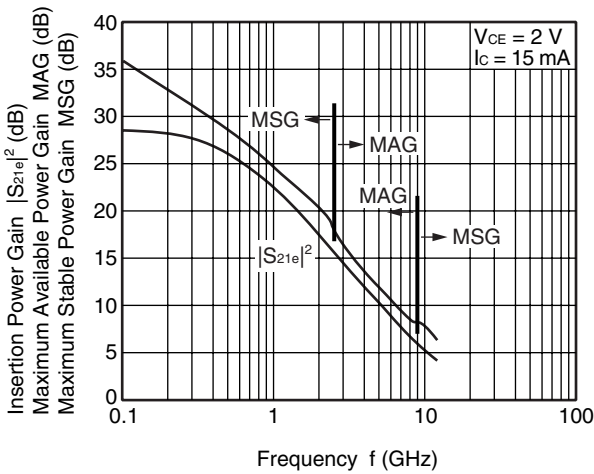
GAIN BANDWIDTH PRODUCT vs. COLLECTOR CURRENT



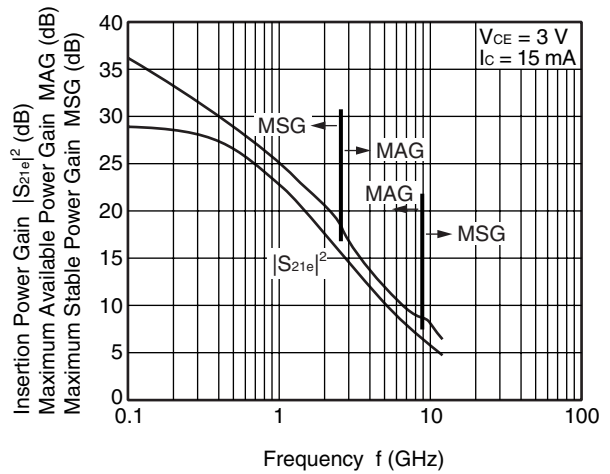
INSERTION POWER GAIN, MAG, MSG vs. FREQUENCY



INSERTION POWER GAIN, MAG, MSG vs. FREQUENCY

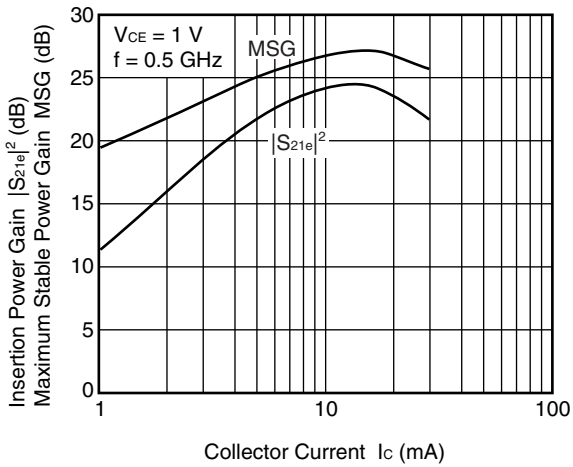


INSERTION POWER GAIN, MAG, MSG vs. FREQUENCY

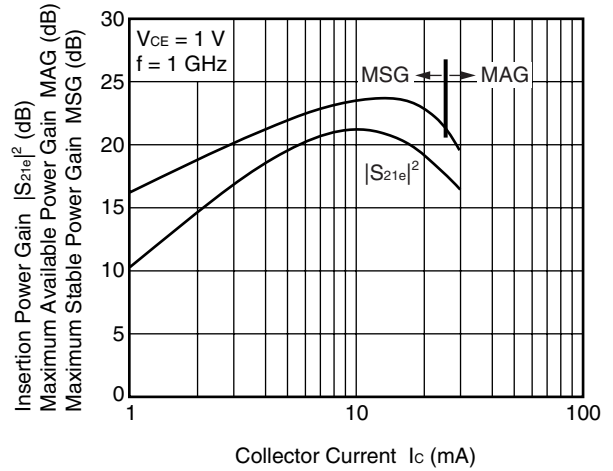


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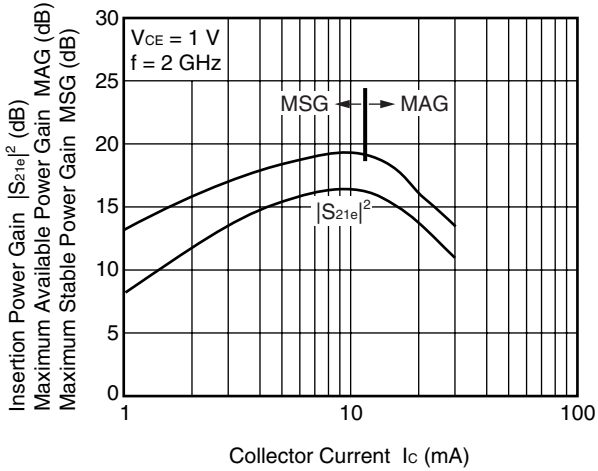
INSERTION POWER GAIN, MSG  
vs. COLLECTOR CURRENT



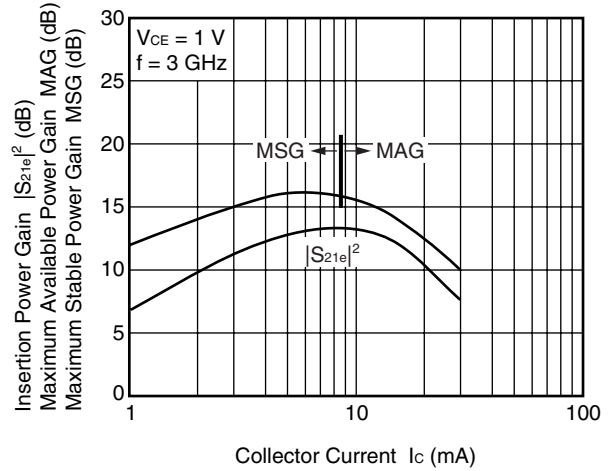
INSERTION POWER GAIN, MAG, MSG  
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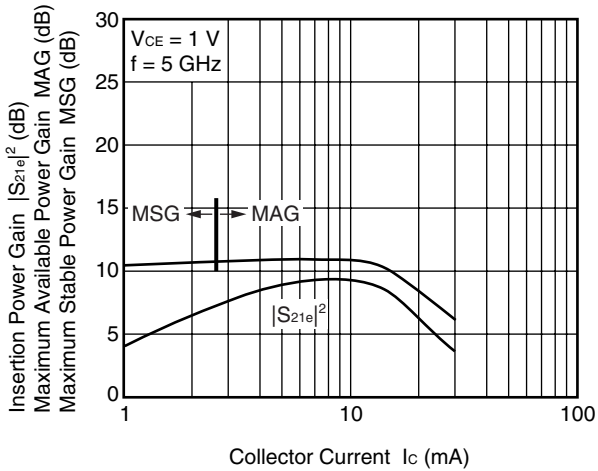
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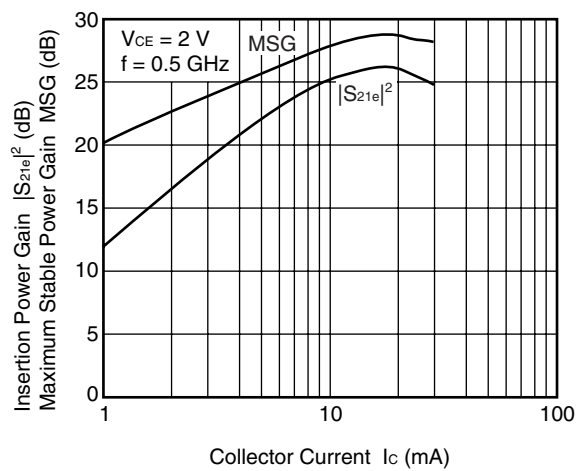
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vs. COLLECTOR CURRENT



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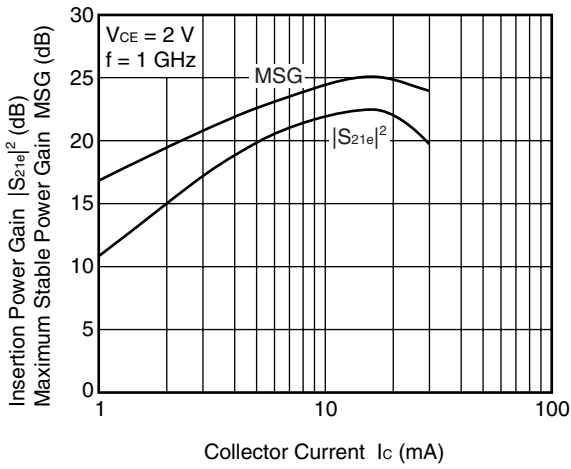


INSERTION POWER GAIN, MSG  
vs. COLLECTOR CURRENT

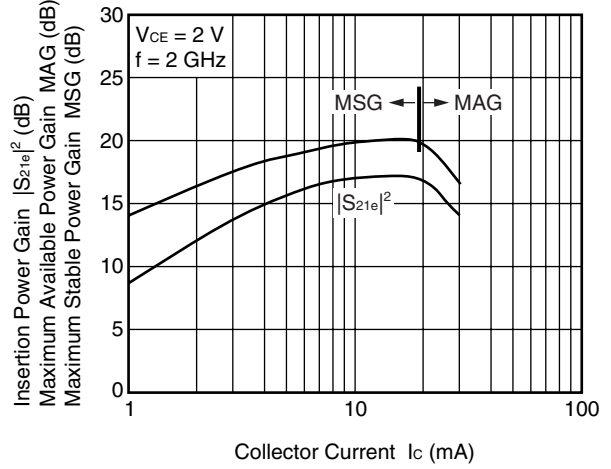


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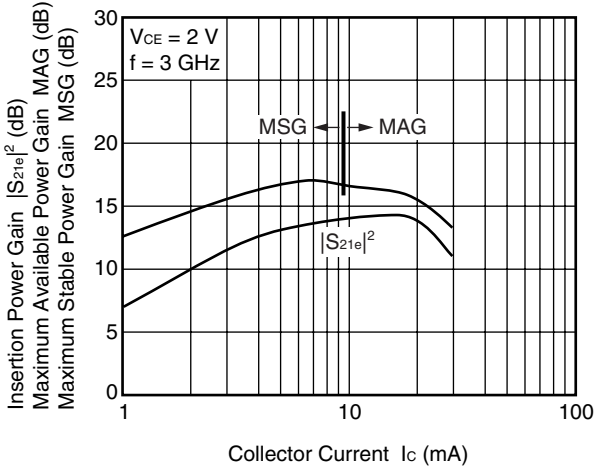
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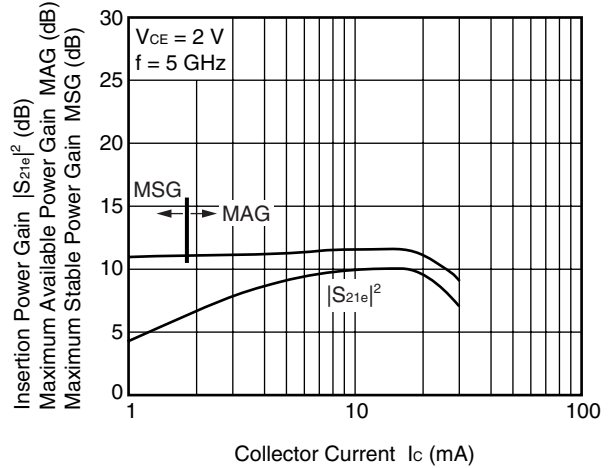
INSERTION POWER GAIN, MAG, MSG  
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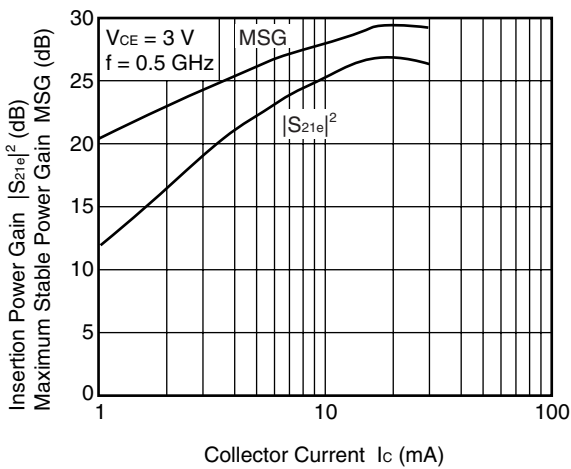
INSERTION POWER GAIN, MAG, MSG  
vs. COLLECTOR CURRENT



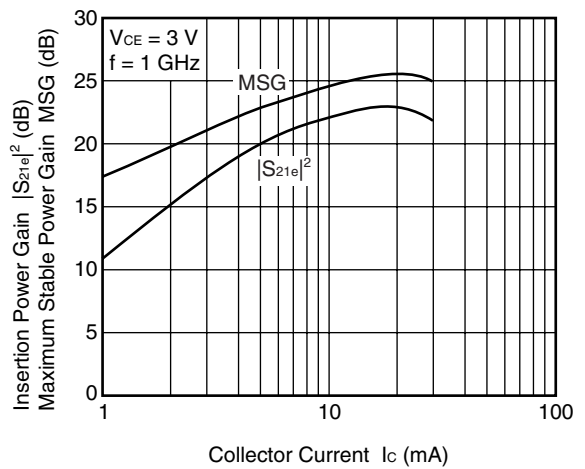
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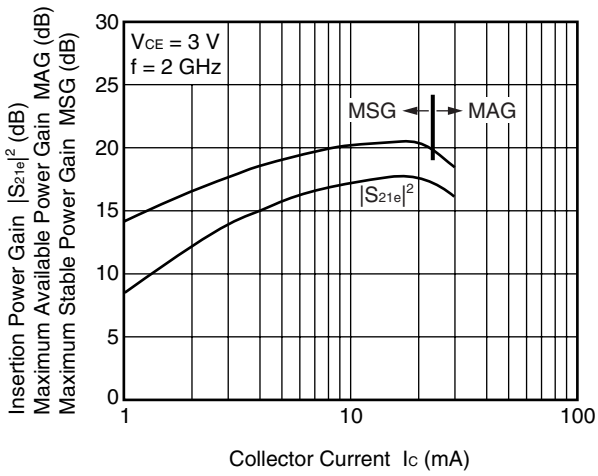


INSERTION POWER GAIN, MSG  
vs. COLLECTOR CURRENT

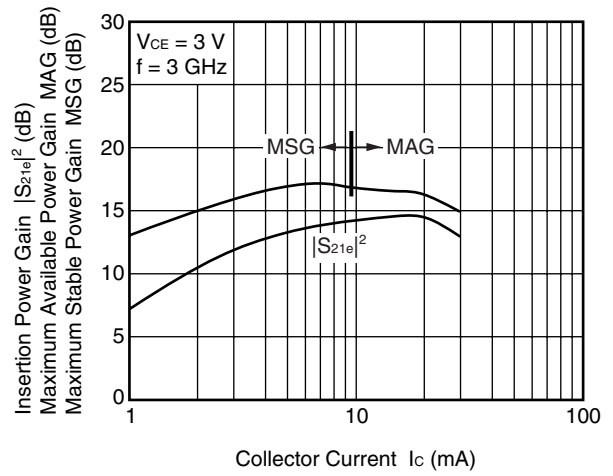


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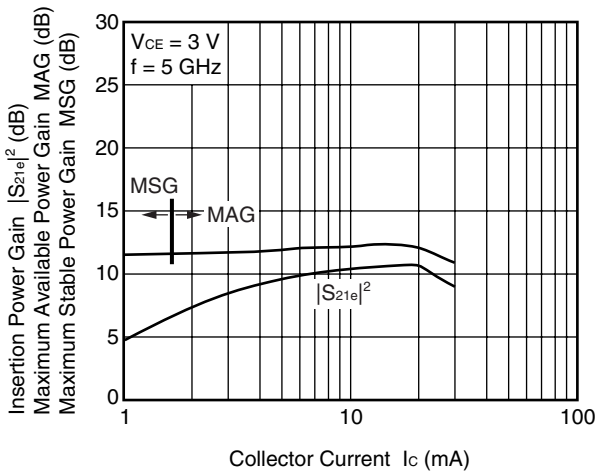
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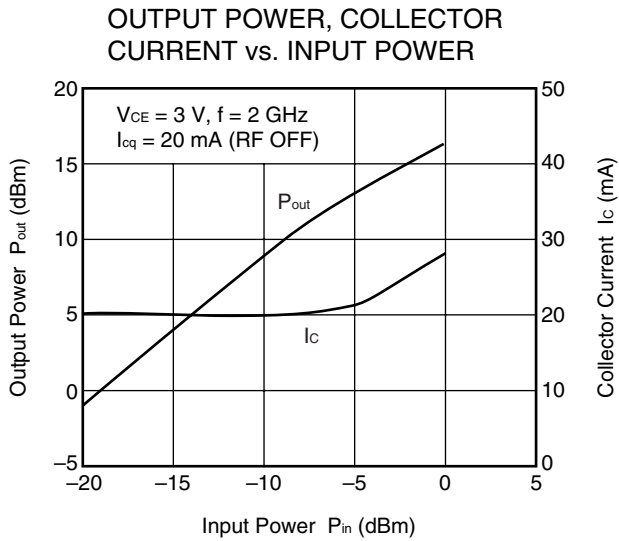


INSERTION POWER GAIN, MAG, MSG  
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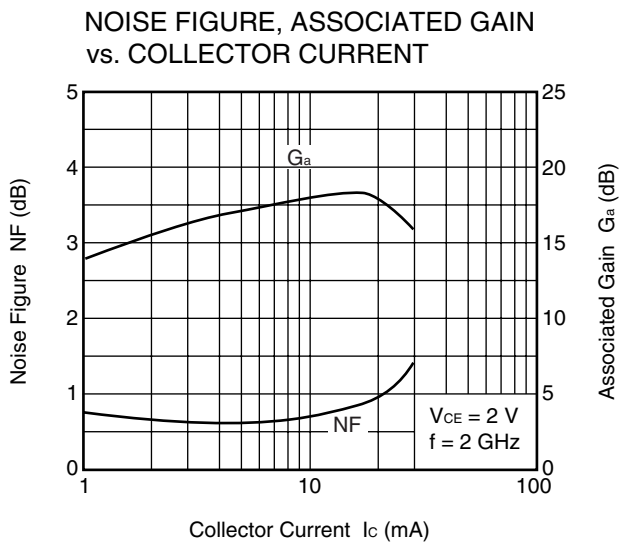


**Remark** The graphs indicate nominal characteristics.





Measuring method : Measured at power matched with external sleeve tuner. (The load resistance is not inserted between the base DC power supply and Bias Tee.)



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<R> **S-PARAMETERS**

S-parameters/Noise parameters are provided on our web site in a form (S2P) that enables direct import to a microwave circuit simulator without keyboard input.

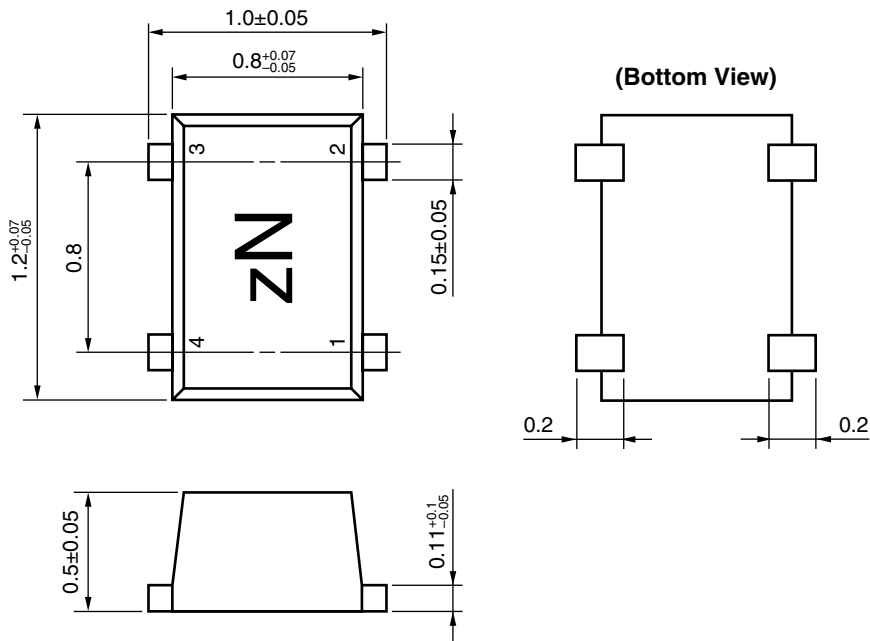
Click here to download S-parameters.

[RF and Microwave] → [Device Parameters]

URL <http://www.ncsd.necel.com/microwave/index.html>

<R> PACKAGE DIMENSIONS

4-PIN LEAD-LESS MINIMOLD (M14, 1208 PACKAGE) (UNIT: mm)



PIN CONNECTIONS

- 1. Collector
- 2. Emitter
- 3. Base
- 4. NC (Connected with Pin 2) Note

**Note** A NC pin is Non-connection in the mold package (When NC-pin is open state, It will get an influences of floating capacitance. Therefore, we recommend connect to NC pin and Emitter pin).

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